

An Introduction to Electronics Systems Packaging

Video Course -2012

L Umanand, DESE, Indian Institute of Science, Bangalore 12

Quiz for Module 8

Thermal Design considerations in systems packaging

Video Sequence 39

- 1. What are the types of heat transfer mechanisms?
- 2. Write short notes on: (i) conduction, (ii) convection, (iii) radiation and (iv) mass transport.
- 3. Write short notes on: (i) specific heat flow rate, (ii) thermal resistance, (iii) thermal resistivity, (iv) thermal co-efficient and (v) thermal conductivity.
- 4. What is the heat flow rate equation? Discuss.
- 5. Calculate thermal resistance to the flow of power through a solid square slab of 100 cm length wherein
 - a) the slab is made up of aluminium with thickness of 10 mm.
 - b) the slab is made up of glass with thickness of 5 mm.
 - c) the slab is made up of steel with thickness of 2 mm.